

MICROWAVE MONOLITHIC INTEGRATED CIRCUIT PACKAGE

Abstract of the Disclosure

A microwave monolithic integrated circuit (MMIC) package includes a MMIC and a base plate that is matched as to its coefficient of thermal expansion (CTE) with the MMIC. A solder preform is contained on the base plate. The MMIC is mounted on the solder preform. A chip cover covers the MMIC and are configured with respective portions that engage each other such that any pads on the MMIC are exposed for wire and ribbon bonding. The base plate and MMIC are secured together by a solder flow process from the solder preform.

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